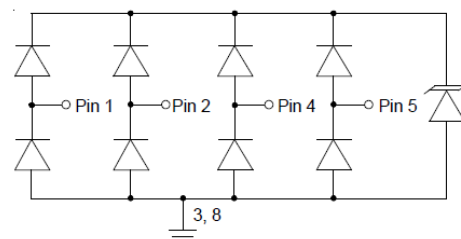


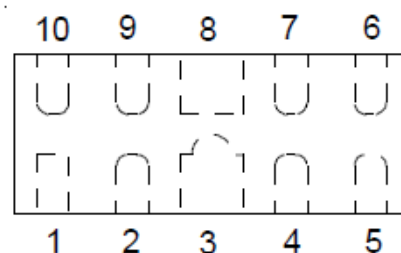
Features

- ◇ 150W (8/20 μ s) Peak Pulse Power
- ◇ Low Capacitance ESD Protection
- ◇ Flow Through DFN2.5x1.0-10L Package
- ◇ RoHS Compliant
- ◇ Matte Tin Lead finish (Pb-Free)
- ◇ Protect Four High Speed Data Lines
- ◇ Meet IEC61000-4-2 Level 4:
 Contact Discharge > 12kV
 Air Discharge > 17kV

Circuit Diagram



PIN Diagram



Applications

- ◇ PCI Express
- ◇ MDDI Ports
- ◇ eSATA Interfaces
- ◇ Display Port Interface
- ◇ Digital Visual Interface (DVI)
- ◇ High Definition Multi-Media Interface (HDMI)

Ordering information

Device	Package	Reel Size	Qty / Reel
RCLAMP0524P	DFN2.5-10-10L	7 inch	3000

Maximum Ratings (Ta = 25°C)

Symbol	Parameter	Value	Unit
PPK	Peak Pulse Power	150	W
IPP	Peak Pulse Current	5	A
VESD (Contact)	Contact ESD Voltage per IEC61000-4-2	12	kV
VESD (Air)	Air ESD Voltage per IEC61000-4-2	17	kV
TJ	Junction Temperature	-55 to +125	°C
TSTG	Storage Temperature	-55 to +150	°C

Electrical Characteristics (Ta = 25℃)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
VRWM	Reverse Working Peak Voltage				5	V
VBR	Reverse Breakdown Voltage	IT = 1mA	6			V
IR	Reverse Leakage Current	VRWM = 5V			1	μA
VC	Clamping Voltage	IPP = 1A (8/20μs)			15	V
CJ	Capacitance	VR = 0V, f = 1MHz Between I/O pins		0.3	0.4	pF
CJ	Capacitance	VR = 0V, f = 1MHz Any I/O pin to ground		0.6	0.8	pF

Typical Performance Curves

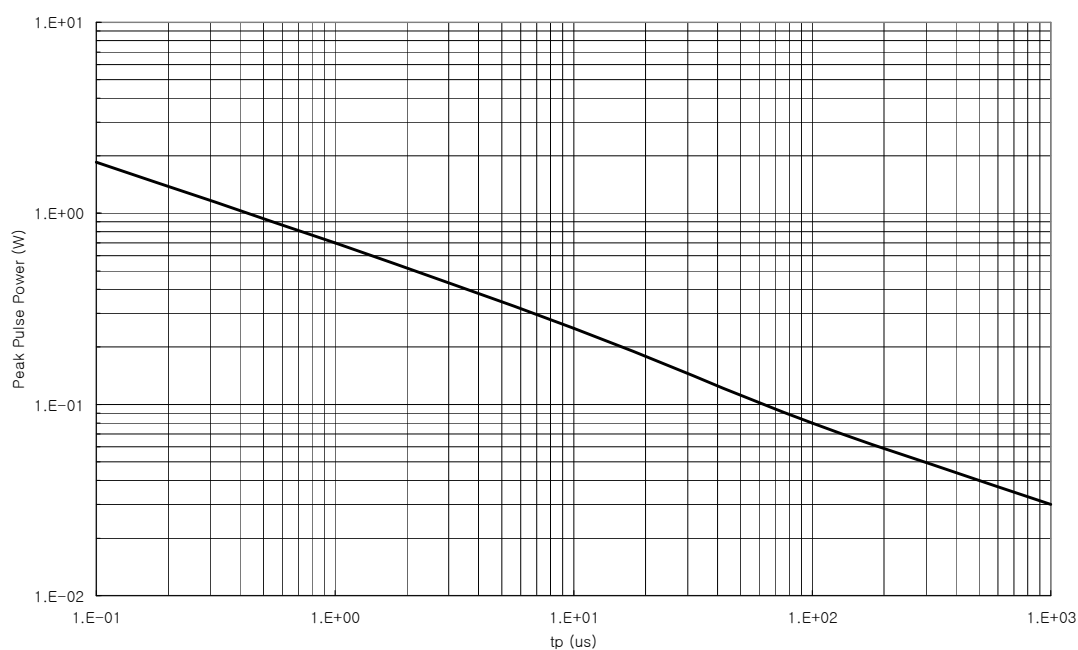


Figure 1. Peak Pulse Power Derating

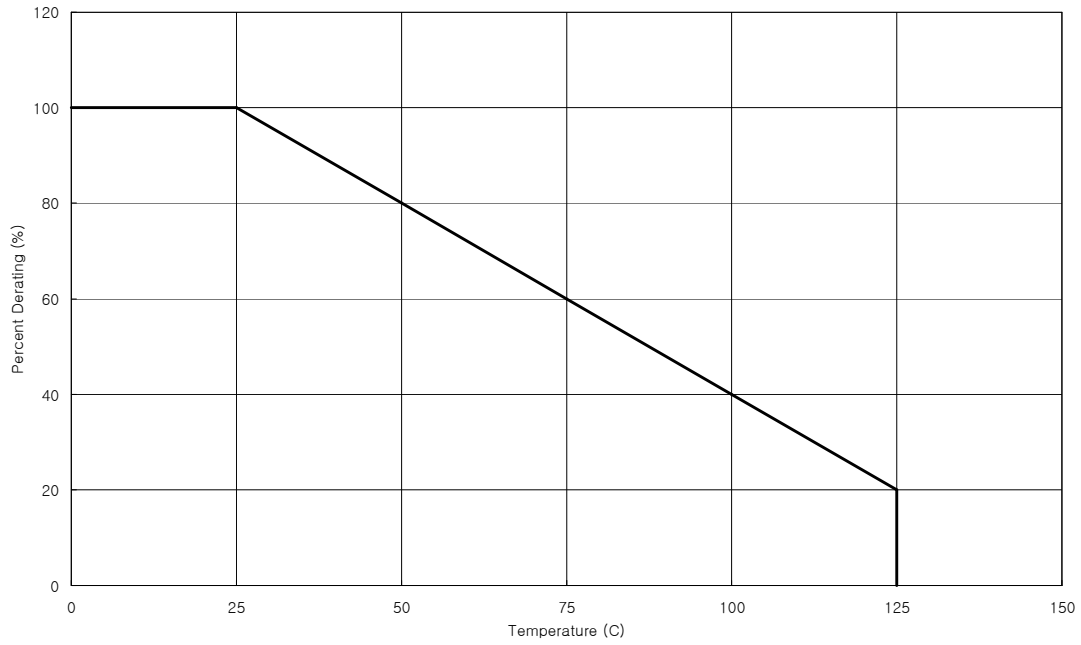


Figure 2. Peak Pulse Power Derating vs Temperature

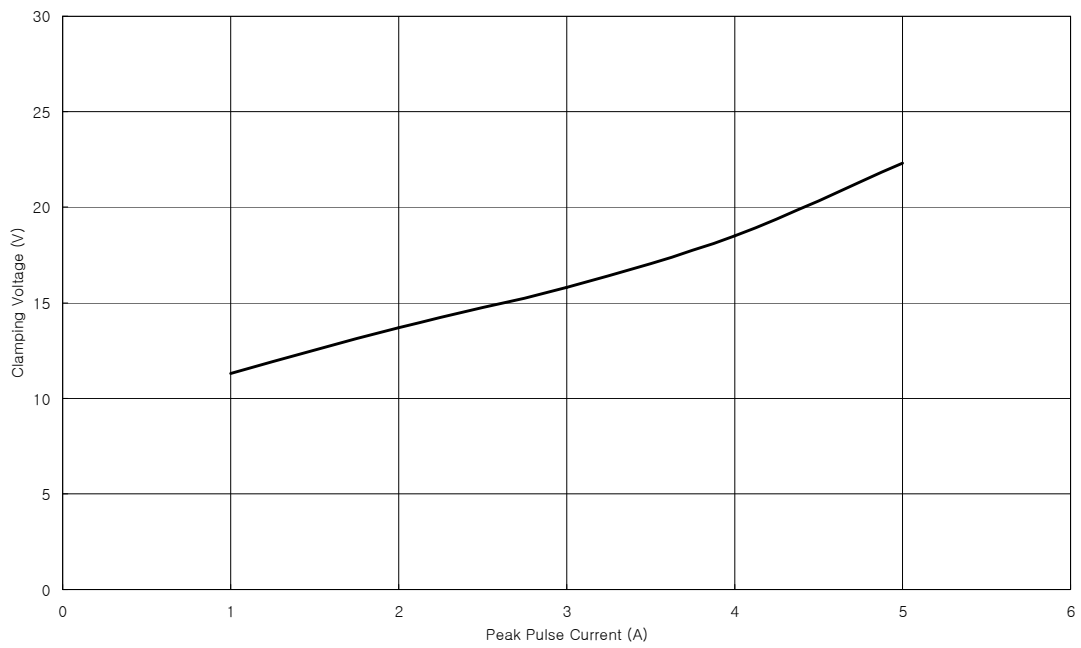


Figure 3. Peak Pulse Current vs Clamping Voltage

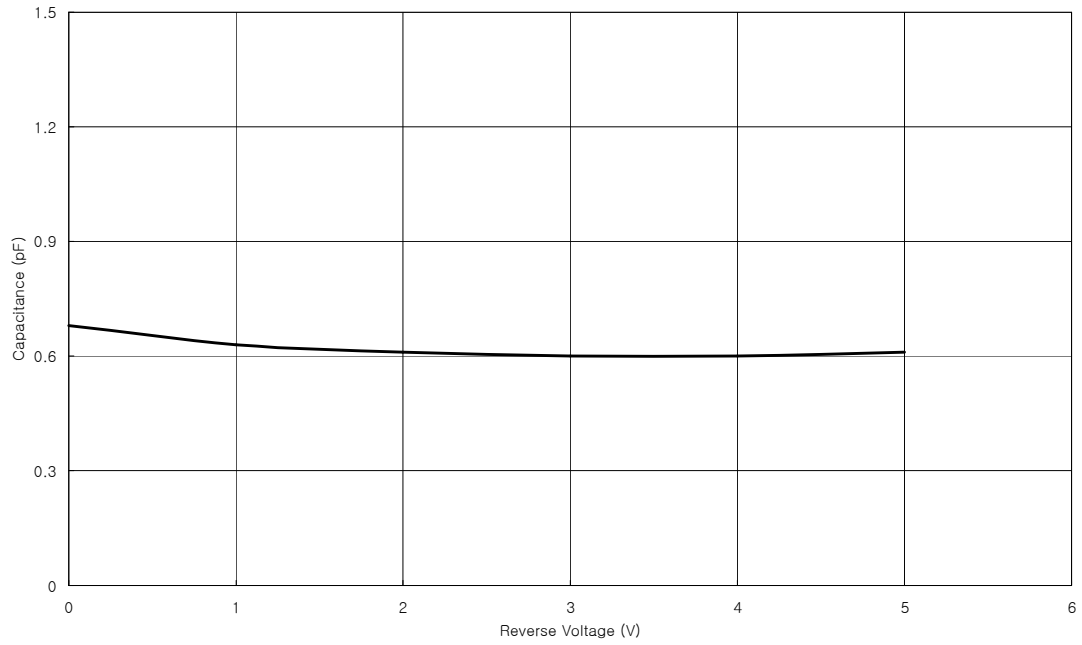
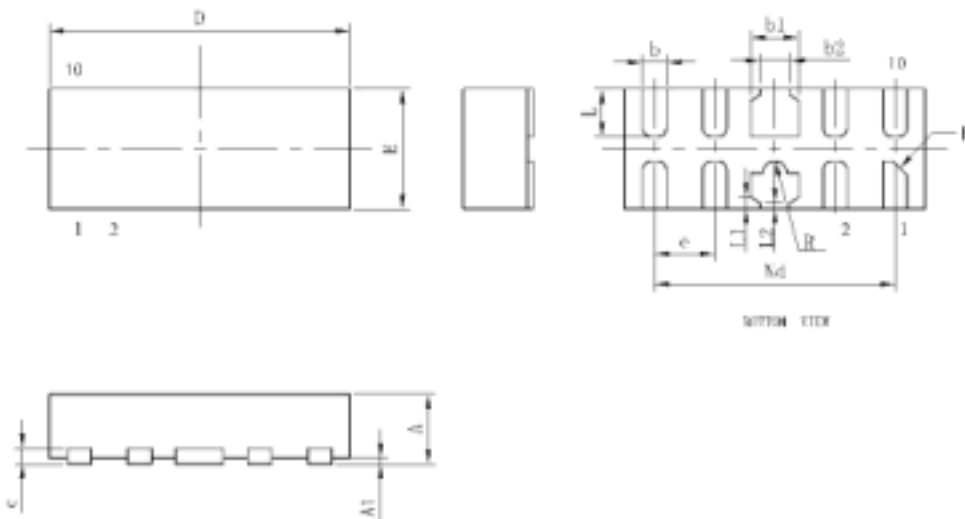


Figure 4. Reverse Voltage vs Capacitance

DFN2.5x1.0-10L Dimension



SYMBOL.	MILLIMETER			△
	MIN	NOM	MAX	
A	0.4	0.48	0.55	△
A1	—	0.02	0.05	
b	0.15	0.20	0.25	
b1	0.35	0.40	0.45	
b2	0.20	0.25	0.30	
e				
D	2.45	2.50	2.55	
e	0.50BSC			
Nd	2.00BSC			
E	0.95	1.00	1.05	
L	0.35	0.40	0.45	
L1	0.075REF			
L2	0.05REF			
h	0.08	0.12	0.15	
R	0.05	0.10	0.15	
1/1 参考尺寸 (ref)				